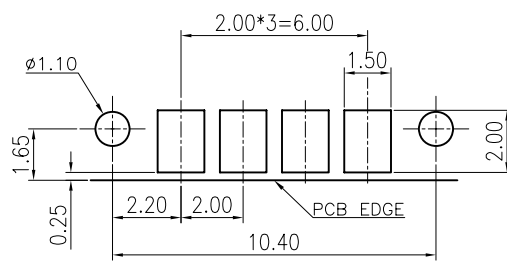
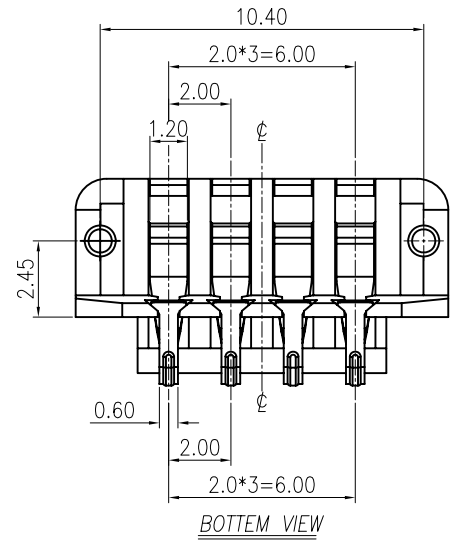
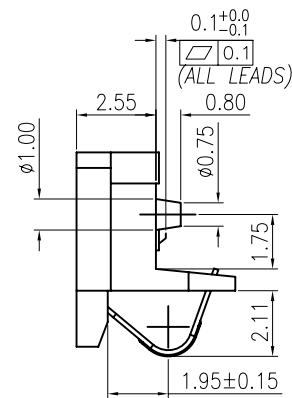
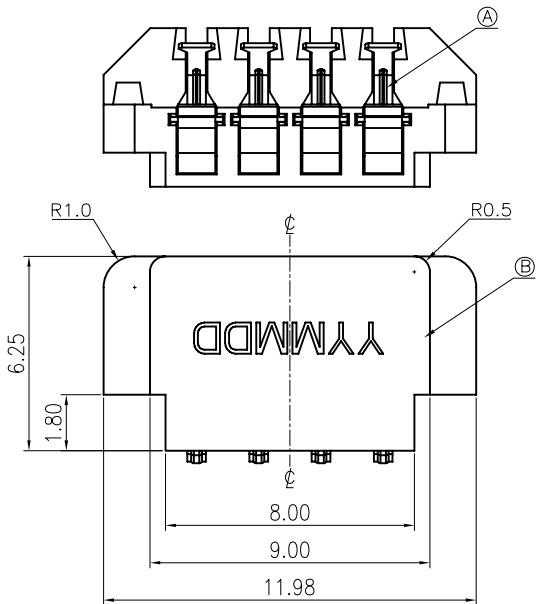


REV.	ECN NO OR DESCRIPTION	REVISED	DATE
A	PRODUCT RELEASE	ZK.CHEN	2006.11.20
B	ADD HF MARK ECN NO:T080204	Steven_hu	2008.11.17



- NOTE:
- MATERIAL:
HOUSING:HIGH TEMP. THERMAL PLASTIC,UL94V-0,COLOR BLACK.
TERMINAL:COPPER ALLOY,T=0.15mm;
 - FINISH:
TERMINAL:30u"~50u" GOLD PLATING ON CONTACT AREA;
100u"~150u" TIN PLATING ON OTHER AREAS;
60u"~180u" NICKEL UNDERPLATING OVERALL.
 - SPECIFICATION:SEE 2.0mm BATTERY SMT TYPE PRODUCT SPEC.
 - SOLDER HEAT RESISTANCE: REFLOW SOLDERING 260° FOR 10SEC.
 - TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.
 - HALOGEN FREE PRODUCT IDENTIFICATION MARK ON PRODUCT:
 - HALOGEN FREE PRODUCT IDENTIFICATION LOGO ON PACKAGING:
 - FOR REFLOW SOLDERING LEED FREE PROCESS.
 - P/N DESCRIPTION:
2BA2001-4P3011

PACKAGE:TAPE AND REEL
HOUSING COLOR:BLACK
CONTACT FINISH:GOLD 30u"~50u" ON CONTACT AREA
CONTACT NO.:4 POSITIONS

B	CONTACT	1	COPPER ALLOY,0.15T	SEE NOTES
A	HOUSING	1	HIGH TEMP. THERMAL PLASTIC	COLOR BLACK
NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
UNLESS OTHERWISE SPECIFED TOLERANCES		Singatron Enterprise Co., Ltd. 信音企業股份有限公司		
DECIMALS:	ANGLES:	TITLE	2.0mm BATTERY 4P 2.55H SMT TYPE	
X :±0.5	X :±2°	DWN	Steven_hu_2008.11.17	PART NO. 2BA2001-4P3011
X.X :±0.3	X.X :±1°	CHKD	苑海洋	SCALE 6:1 UNIT: mm
X.XX :±0.2		APVD	ROBIN	SIZE: A3 SHEET: 10F1 REV: B
CUSTOMER COPY				